LFM-48 SUC

1. Can stably maintain printing amount and shapes even with continuous printing.
2. Upper wettability is good towards products even with atmospheric reflow. Forms a stable fillet. Reduces N2 use and can contribute to CO2 reduction by reducing energy consumption, major running costs.
3. Good wettability even towards metals such as Ni. And of course has an effect against BGA non-wettiness.
4. Ensures the reliability of flux. Can freely use without washing on products from a large range of fields.

<table>
<thead>
<tr>
<th>Product Name</th>
<th>UMS-48(SU)</th>
<th>UMS-48HV(SU)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Alloy Name</td>
<td>LFM-48</td>
<td></td>
</tr>
<tr>
<td>Flux Name</td>
<td>SUC</td>
<td></td>
</tr>
<tr>
<td>Melting Temp.</td>
<td>217±2°C</td>
<td></td>
</tr>
<tr>
<td>Type of Powder</td>
<td>W</td>
<td></td>
</tr>
<tr>
<td>Powder Size</td>
<td>16.2μm</td>
<td>26μm</td>
</tr>
<tr>
<td>Flux Content</td>
<td>1.6%</td>
<td></td>
</tr>
<tr>
<td>Viscosity</td>
<td>2/0.330</td>
<td></td>
</tr>
<tr>
<td>Noctic value</td>
<td>0.42±0.50</td>
<td></td>
</tr>
</tbody>
</table>

- SUC on all metals
- Good Confirm the wettability of materials that do not adhere well.
- Conditions: Target Metals: Ni, 42 Alloy (Au=2%) Nickel-tin (SN)-base (C65)
- Part Shape: 30×30×1.3mm
- Melt with: 200°C, 20µm
- Printing amount: 0.65±0.0005

- Continuous Printing Test
- Confirm the adhesion stability during continuous printing and reliability of temporary drop printing.
- Condition: Printer: Panasonic 400µA
- Mask: SU-300 µm
- Printing speed: 0.3m/min
- Feeder speed: 0.3m/min
- Temperature: 25°C
- Amount of BGA: 0.5mm HDP (1000×500×2mm)
- Test product: SUC

- Soak test (0.5mm HDP)
- Atmospheric: 24 hours
- No Flux

- Solder Paste Product Names and Structure

- Solder Paste Product Specifications

- Flux Name | Alloy composition | Melting Temp. | Powder Size | Flux Content | Viscosity |
<table>
<thead>
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<tbody>
<tr>
<td>SUC</td>
<td>LFM-48(5n-3Ag-0.5Cu)</td>
<td>217±2°C</td>
<td>W: 20-38µm</td>
<td>11.5%</td>
<td>220Pas</td>
</tr>
</tbody>
</table>

- When your ordered product is out-of-stock, please contact our sales representative.

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